

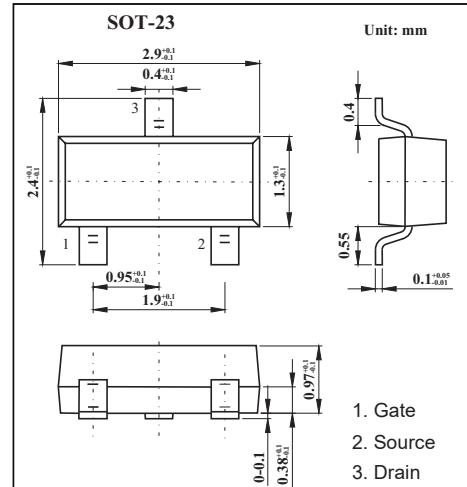
## SOT-23 Plastic-Encapsulate MOSFETs

### FEATURES

- V<sub>DS</sub> (V) = 30V
- I<sub>D</sub> = 4 A
- R<sub>DS(ON)</sub> < 5.5mΩ (V<sub>GS</sub> = 10V)
- R<sub>DS(ON)</sub> < 7.0mΩ (V<sub>GS</sub> = 4.5V)
- R<sub>DS(ON)</sub> < 1.10mΩ (V<sub>GS</sub> = 2.5V)
- N-Channel Enhancement Mode Field Effect Transistor

### MECHANICAL DATA

- Case style: SOT-23 molded plastic
- Mounting position: any



### MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current TA=25°C	I <sub>D</sub>	4	A
TA=70°C		3.4	
Pulsed Drain Current	I <sub>DM</sub>	15	
Power Dissipation TA=25°C	P <sub>D</sub>	1.4	W
TA=70°C		1	
Thermal Resistance.Junction-to-Ambient	R <sub>θ JA</sub>	125	°C/W
Thermal Resistance.Junction-to-Case	R <sub>θ JC</sub>	80	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

**MOSFET ELECTRICAL CHARACTERISTICS** Ta=25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =250 μ A, V <sub>GS</sub> =0V	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			1	μ A
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			5	
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250 μ A	0.6	1	1.4	V
Static Drain-Source On-Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4A		45	55	mΩ
		V <sub>GS</sub> =10V, I <sub>D</sub> =4A T <sub>J</sub> =125°C		66	80	
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A		55	70	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A		83	110	mΩ
On state drain current	I <sub>D(on)</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V	10			A
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =4A		8		S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		390		pF
Output Capacitance	C <sub>oss</sub>			54.5		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			41		pF
Gate resistance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		3		Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =15V, I <sub>D</sub> =-4A		4.34		nC
Gate Source Charge	Q <sub>gs</sub>			0.6		nC
Gate Drain Charge	Q <sub>gd</sub>			1.38		nC
Turn-On DelayTime	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =3.75 Ω, R <sub>GEN</sub> =6 Ω		3.3		ns
Turn-On Rise Time	t <sub>r</sub>			1		ns
Turn-Off DelayTime	t <sub>D(off)</sub>			21.7		ns
Turn-Off Fall Time	t <sub>f</sub>			2.1		ns
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =4A, dI/dt=100A/ μ s		12		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =4A, dI/dt=100A/ μ s		6.3		nC
Maximum Body-Diode Continuous Current	I <sub>s</sub>				2.5	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>s</sub> =1A, V <sub>GS</sub> =0V		0.8	1	V